## Switch-mode Power Rectifier

### **DPAK Surface Mount Package**

This switch-mode power rectifier which uses the Schottky Barrier principle with a proprietary barrier metal, is designed for use as output rectifiers, free wheeling, protection and steering diodes in switching power supplies, inverters and other inductive switching circuits.

#### **Features**

- Low Forward Voltage
- 150°C Operating Junction Temperature
- Epoxy Meets UL 94 V-0 @ 0.125 in
- Compact Size
- Lead Formed for Surface Mount
- SBRD8 Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free and are RoHS Compliant

#### **Mechanical Characteristics**

- Case: Epoxy, Molded
- Weight: 0.4 Gram (Approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- Shipped 75 Units Per Plastic Tube
- ESD Rating:
  - Machine Model = C (> 400 V)
  - Human Body Model = 3B (> 8000 V)



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# SCHOTTKY BARRIER RECTIFIER 8.0 AMPERES, 35 VOLTS





#### **MARKING DIAGRAM**



B835LG = Specific Device Number
A = Assembly Location\*

Y = Year WW = Work Week G = Pb-Free Device

#### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
MBRD835LG	DPAK (Pb-Free)	75 Units / Rail
SBRD8835LG	DPAK (Pb-Free)	75 Units / Rail
SBRD8835LG-VF01	DPAK (Pb-Free)	75 Units / Rail
MBRD835LT4G	DPAK (Pb-Free)	2,500 / Tape & Reel
SBRD835LT4G-VF01	DPAK (Pb-Free)	2,500 / Tape & Reel
SBRD8835LT4G	DPAK (Pb-Free)	2,500 / Tape & Reel
SBRD8835LT4G-VF01	DPAK (Pb-Free)	2,500 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure BRD8011/D

<sup>\*</sup> The Assembly Location Code (A) is front side optional. In cases where the Assembly Location is stamped in the package bottom (molding ejecter pin), the front side assembly code may be blank.

#### **MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V <sub>RRM</sub> V <sub>RWM</sub> V <sub>R</sub>	35	<b>V</b>
Average Rectified Forward Current (At Rated V <sub>R</sub> , T <sub>C</sub> = 88°C)	I <sub>F(AV)</sub>	8.0	Α
Peak Repetitive Forward Current (At Rated V <sub>R</sub> , Square Wave, 20 kHz, T <sub>C</sub> = 80°C)	I <sub>FRM</sub>	16	Α
Non-Repetitive Peak Surge Current (Surge applied at rated load conditions, halfwave, single phase, 60 Hz)	I <sub>FSM</sub>	75	Α
Repetitive Avalanche Current (Current Decaying Linearly to Zero in 1 μs, Frequency Limited by T <sub>Jmax</sub> )	I <sub>AR</sub>	2.0	Α
Storage / Operating Case Temperature	T <sub>stg</sub>	-65 to +150	°C
Operating Junction Temperature (Note 1)	TJ	-65 to +150	°C
Voltage Rate of Change (Rated V <sub>R</sub> )	dv/dt	10,000	V/μs

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

#### THERMAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit
Thermal Resistance – Junction-to-Case	$R_{ heta JC}$	2.8	°C/W
Thermal Resistance – Junction–to–Ambient (Note 2)	$R_{ heta JA}$	80	°C/W

<sup>2.</sup> Rating applies when surface mounted on the minimum pad size recommended.

#### **ELECTRICAL CHARACTERISTICS**

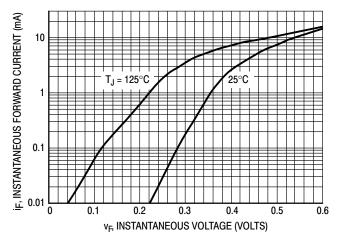
Characteristic	Symbol	Value	Unit
Maximum Instantaneous Forward Voltage (Note 3) ( $i_F = 8 \text{ Amps}, T_C = +25^{\circ}\text{C}$ ) ( $i_F = 8 \text{ Amps}, T_C = +125^{\circ}\text{C}$ )	V <sub>F</sub>	0.51 0.41	V
Maximum Instantaneous Reverse Current (Note 3) (Rated dc Voltage, $T_C = +25^{\circ}C$ ) (Rated dc Voltage, $T_C = +100^{\circ}C$ )	I <sub>R</sub>	1.4 35	mA

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

<sup>1.</sup> The heat generated must be less than the thermal conductivity from Junction-to-Ambient:  $dP_D/dT_J < 1/R_{\theta JA}$ .

<sup>3.</sup> Pulse Test: Pulse Width = 300  $\mu$ s, Duty Cycle  $\leq$  2%.

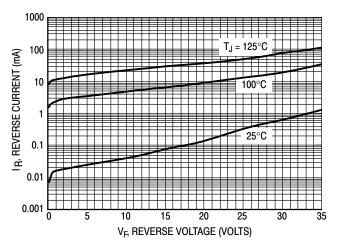
#### **TYPICAL CHARACTERISTICS**



10 T<sub>J</sub> = 125°C T<sub></sub>

Figure 1. Maximum Forward Voltage

Figure 2. Typical Forward Voltage



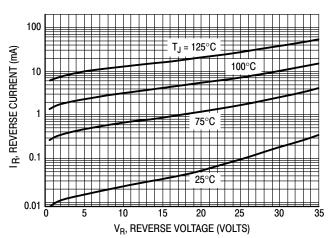


Figure 3. Maximum Reverse Current

Figure 4. Typical Reverse Current

#### **TYPICAL CHARACTERISTICS**

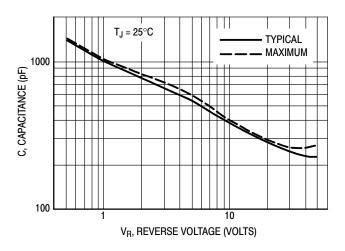


Figure 5. Maximum and Typical Capacitance

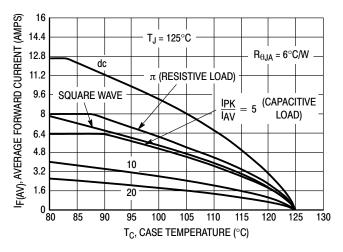


Figure 6. Current Derating, Infinite Heatsink

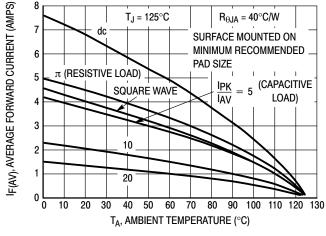


Figure 7. Current Derating

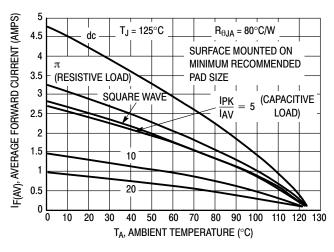


Figure 8. Current Derating, Free Air

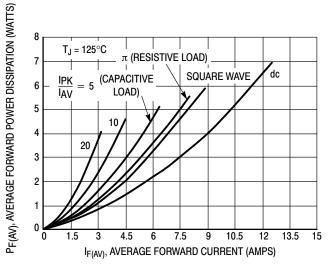
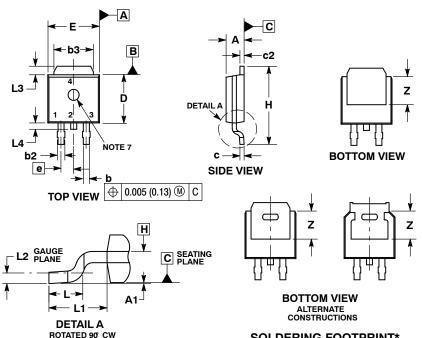


Figure 9. Forward Power Dissipation

#### PACKAGE DIMENSIONS

#### **DPAK (SINGLE GAUGE)**

CASE 369C ISSUE F



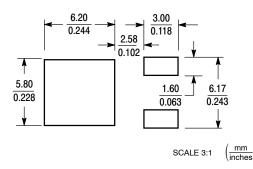
- OTLS.

  1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.

  2. CONTROLLING DIMENSION: INCHES.
- 3. THERMAL PAD CONTOUR OPTIONAL WITHIN DI-MENSIONS b3, L3 and Z.
  4. DIMENSIONS D AND E DO NOT INCLUDE MOLD
- FLASH, PROTRUSIONS, OR BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.006 INCHES PER SIDE.
  5. DIMENSIONS D AND E ARE DETERMINED AT THE
- OUTERMOST EXTREMES OF THE PLASTIC BODY.
- 6. DATUMS A AND B ARE DETERMINED AT DATUM
- 7. OPTIONAL MOLD FEATURE.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
Α	0.086	0.094	2.18	2.38
A1	0.000	0.005	0.00	0.13
b	0.025	0.035	0.63	0.89
b2	0.028	0.045	0.72	1.14
b3	0.180	0.215	4.57	5.46
C	0.018	0.024	0.46	0.61
c2	0.018	0.024	0.46	0.61
D	0.235	0.245	5.97	6.22
Е	0.250	0.265	6.35	6.73
е	0.090 BSC		2.29 BSC	
Н	0.370	0.410	9.40	10.41
L	0.055	0.070	1.40	1.78
L1	0.114	REF	2.90	REF
L2	0.020	BSC	0.51 BSC	
L3	0.035	0.050	0.89	1.27
L4		0.040		1.01
Z	0.155		3.93	

#### **SOLDERING FOOTPRINT\***



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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